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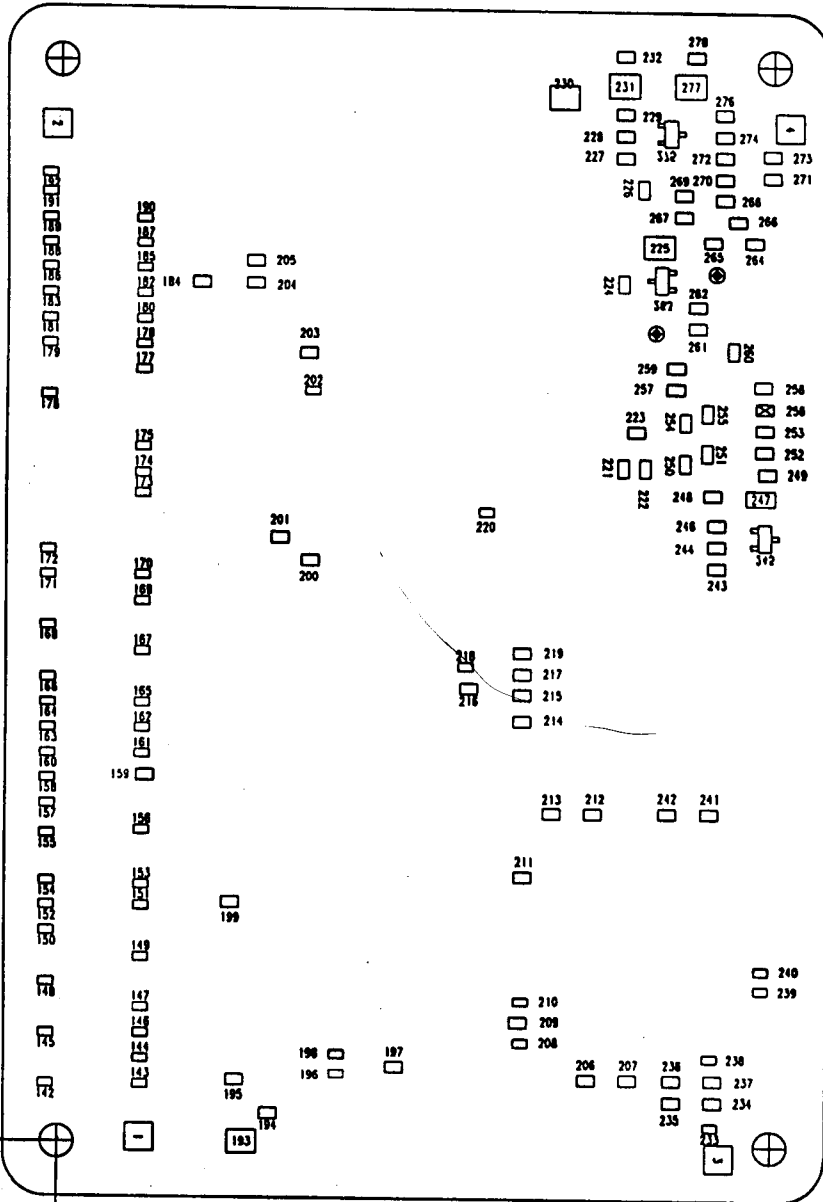
OF CIRCUIT BOARD

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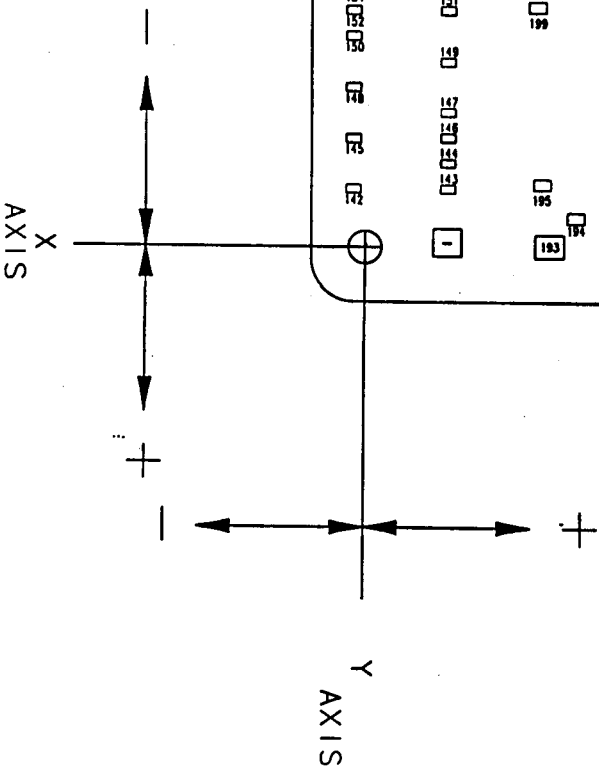
SOLDER PASTE ITEM 3 PER PROCESS SPECIFICATION

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DELPHI DELCO ELECTRONICS SYSTEMS
DIVISION OF DELPHI AUTOMOTIVE



VIEWS FROM WAVE SOLDER SIDE
OF CIRCUIT BOARD



NOTES:

1.

SECURE SMC'S TO THE WAVE SOLDER SIDE OF THE CIRCUIT BOARD PERPROCESS
SPECIFICATION USING PRIMARY ADHESIVE ITEM 2 OR OPTIONAL ADHESIVE
ITEM 3.